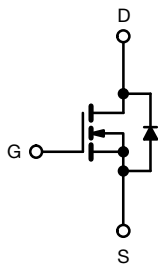
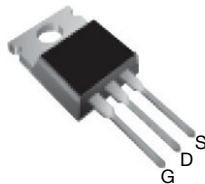


## Power MOSFET

**TO-220AB**


N-Channel MOSFET

### FEATURES

- Lower gate charge  $Q_g$  results in simpler drive requirements
- Improved gate, avalanche, and dynamic  $dV/dt$  ruggedness
- Fully characterized capacitance and avalanche voltage
- Material categorization: for definitions of compliance please see [www.vishay.com/doc?99912](http://www.vishay.com/doc?99912)


**RoHS\***  
Available

### Note

\* This datasheet provides information about parts that are RoHS-compliant and / or parts that are non RoHS-compliant. For example, parts with lead (Pb) terminations are not RoHS-compliant. Please see the information / tables in this datasheet for details

### APPLICATIONS

- Switch mode power supply (SMPS)
- Uninterruptible power supplies
- High speed power switching

### PRODUCT SUMMARY

|                           |                        |       |
|---------------------------|------------------------|-------|
| $V_{DS}$ (V)              | 500                    |       |
| $R_{DS(on)}$ ( $\Omega$ ) | $V_{GS} = 10\text{ V}$ | 0.450 |
| $Q_g$ max. (nC)           | 81                     |       |
| $Q_{gs}$ (nC)             | 20                     |       |
| $Q_{gd}$ (nC)             | 36                     |       |
| Configuration             | Single                 |       |

### ORDERING INFORMATION

|                |               |
|----------------|---------------|
| Package        | TO-220AB      |
| Lead (Pb)-free | IRFB13N50APbF |

### ABSOLUTE MAXIMUM RATINGS ( $T_C = 25\text{ }^\circ\text{C}$ , unless otherwise noted)

| PARAMETER   |                         |                         | SYMBOL                            | LIMIT       | UNIT     |
|---|-------------------------|-------------------------|-----------------------------------|-------------|----------|
| Drain-source voltage                                      |                         |                         | V <sub>DS</sub>                   | 500         | V        |
| Gate-source voltage                                       |                         |                         | V <sub>GS</sub>                   | ± 30        |          |
| Continuous drain current                                  | V <sub>GS</sub> at 10 V | T <sub>C</sub> = 25 °C  | I <sub>D</sub>                    | 14          | A        |
|   |                         | T <sub>C</sub> = 100 °C |                                   | 9.1         |          |
| Pulsed drain current <sup>a</sup>                         |                         |                         | I <sub>DM</sub>                   | 56          |          |
| Linear derating factor                                    |                         |                         |                                   | 2.0         | W/°C     |
| Single pulse avalanche energy <sup>b</sup>                |                         |                         | E <sub>AS</sub>                   | 560         | mJ       |
| Repetitive avalanche current <sup>a</sup>                 |                         |                         | I <sub>AR</sub>                   | 14          | A        |
| Repetitive avalanche energy <sup>a</sup>                  |                         |                         | E <sub>AR</sub>                   | 25          | mJ       |
| Maximum power dissipation                                 | T <sub>C</sub> = 25 °C  |                         | P <sub>D</sub>                    | 250         | W        |
| Peak diode recovery dV/dt <sup>c</sup>                    |                         |                         | dV/dt                             | 9.2         | V/ns     |
| Operating junction and storage temperature range          |                         |                         | T <sub>J</sub> , T <sub>stg</sub> | -55 to +150 | °C       |
| Soldering recommendations (peak temperature) <sup>d</sup> | For 10 s                |                         |                                   | 300         |          |
| Mounting torque   | 6-32 or M3 screw        |                         |                                   | 10          | lbf · in |
|   |                         |                         |                                   | 1.1         | N · m    |

### Notes

- Repetitive rating; pulse width limited by maximum junction temperature (see fig. 11)
- Starting  $T_J = 25\text{ }^\circ\text{C}$ ,  $L = 5.7\text{ mH}$ ,  $R_g = 25\text{ }\Omega$ ,  $I_{AS} = 14\text{ A}$ ,  $dV/dt = 7.6\text{ V/ns}$  (see fig. 12a)
- $I_{SD} \leq 14\text{ A}$ ,  $dI/dt \leq 250\text{ A}/\mu\text{s}$ ,  $V_{DD} \leq V_{DS}$ ,  $T_J \leq 150\text{ }^\circ\text{C}$
- 1.6 mm from case

**THERMAL RESISTANCE RATINGS**

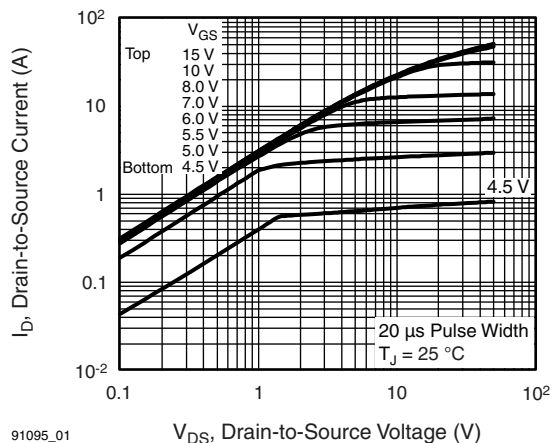
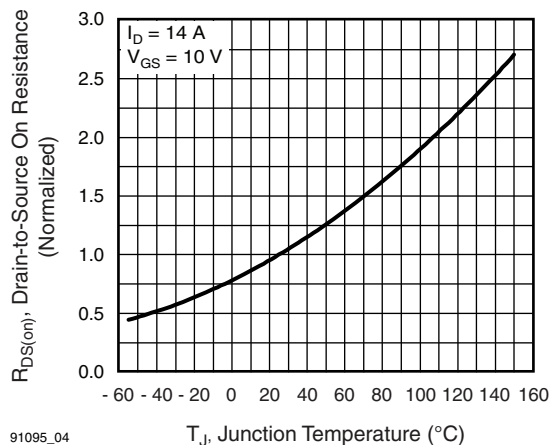
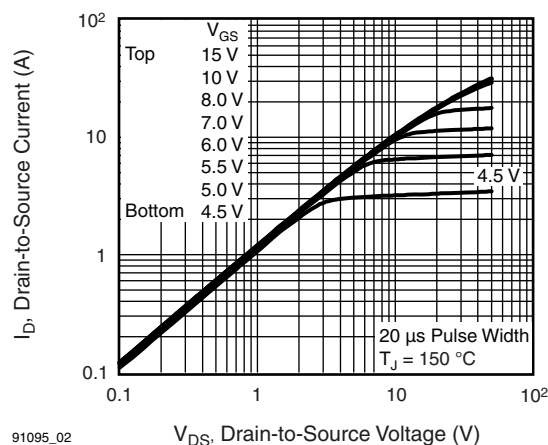
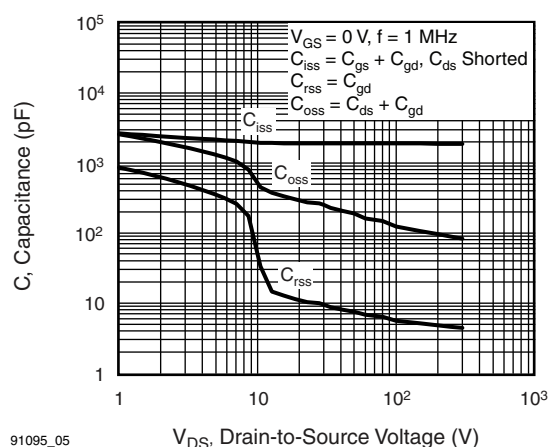
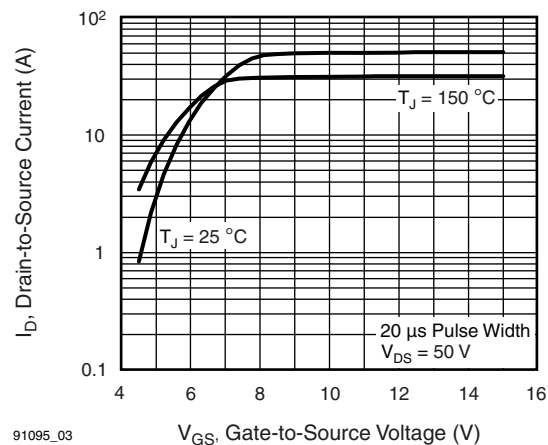
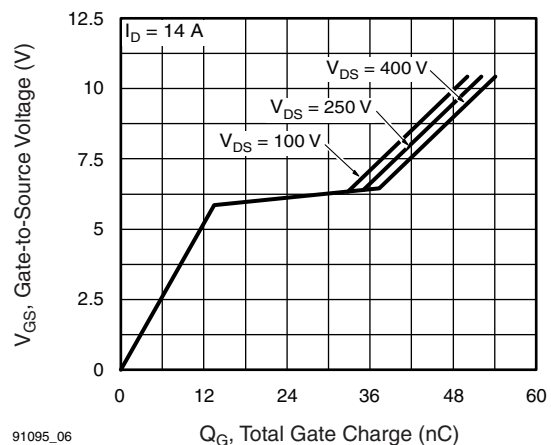
| PARAMETER                           | SYMBOL     | TYP. | MAX. | UNIT |
|-------------------------------------|------------|------|------|------|
| Maximum junction-to-ambient         | $R_{thJA}$ | -    | 62   | °C/W |
| Case-to-sink, flat, greased surface | $R_{thCS}$ | 0.50 | -    |      |
| Maximum junction-to-case (drain)    | $R_{thJC}$ | -    | 0.50 |      |

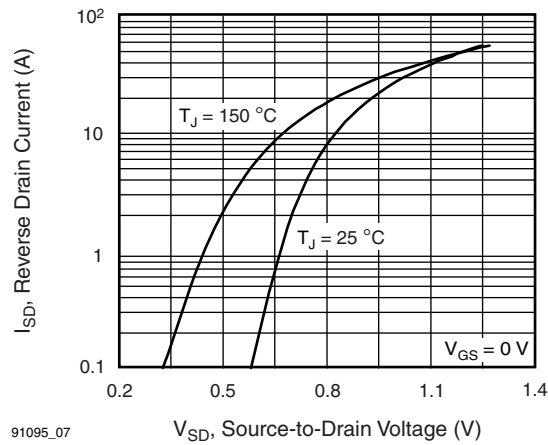
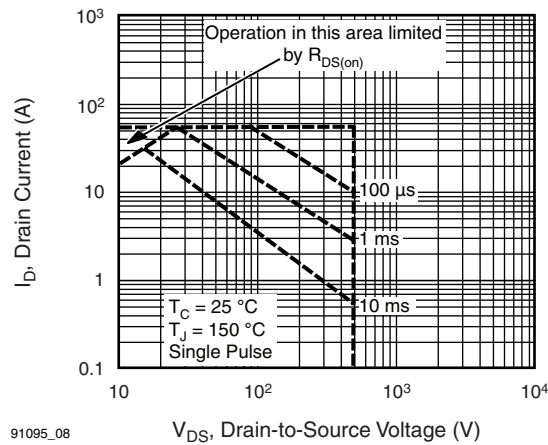
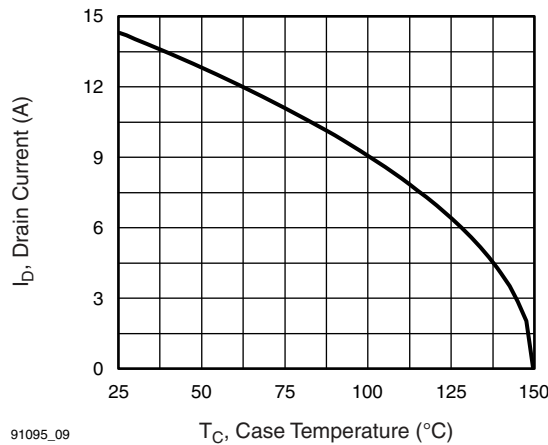
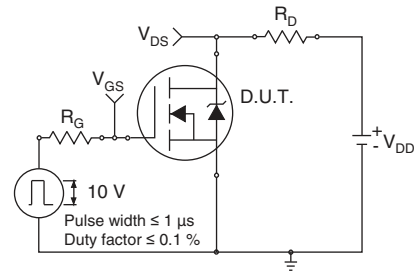
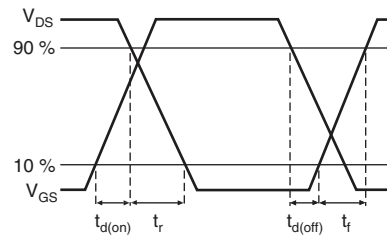
**SPECIFICATIONS** ( $T_J = 25\text{ }^{\circ}\text{C}$ , unless otherwise noted)

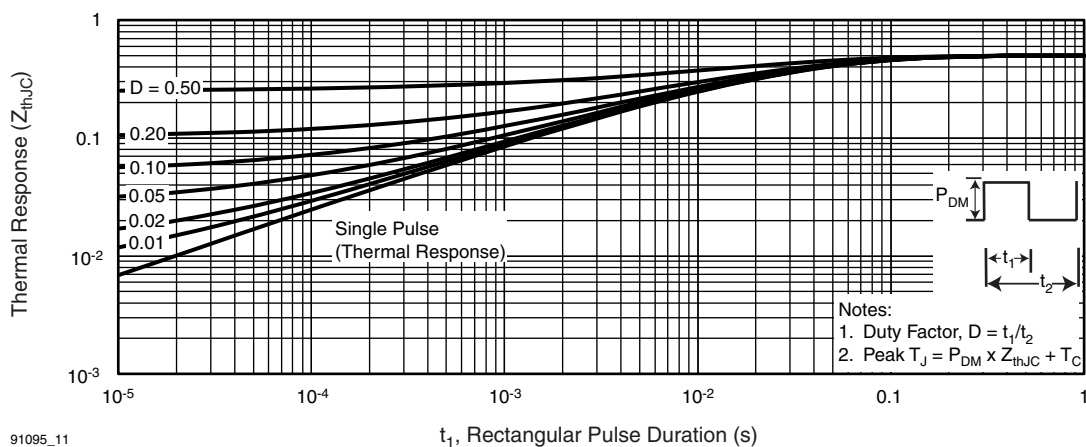
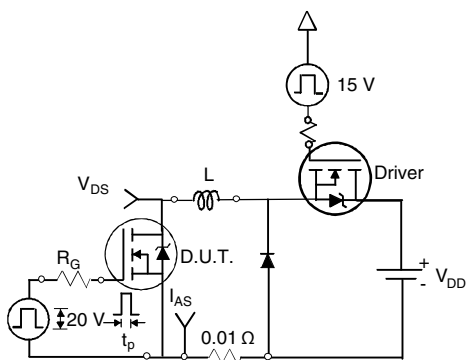
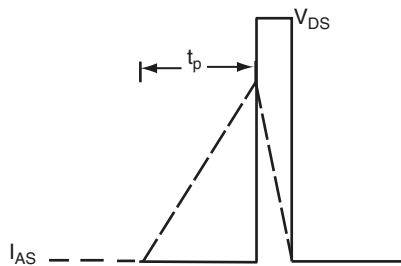
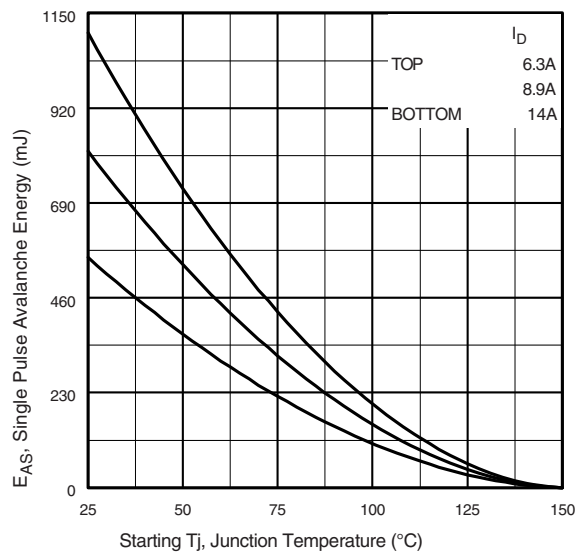
| PARAMETER                                 | SYMBOL                | TEST CONDITIONS  |  | MIN. | TYP. | MAX.      | UNIT                  |
|---|-----------------------|--|--|------|------|-----------|-----------------------|
| Static                                    |                       |  |  |      |      |           |                       |
| Drain-source breakdown voltage            | $V_{DS}$              | $V_{GS} = 0\text{ V}$ , $I_D = 250\text{ }\mu\text{A}$   |  | 500  | -    | -         | V                     |
| $V_{DS}$ temperature coefficient          | $\Delta V_{DS}/T_J$   | Reference to $25\text{ }^{\circ}\text{C}$ , $I_D = 1\text{ mA}$  |  | -    | 0.55 | -         | V/ $^{\circ}\text{C}$ |
| Gate-source threshold voltage             | $V_{GS(th)}$          | $V_{DS} = V_{GS}$ , $I_D = 250\text{ }\mu\text{A}$   |  | 2.0  | -    | 4.0       | V                     |
| Gate-source leakage                       | $I_{GSS}$             | $V_{GS} = \pm 30\text{ V}$   |  | -    | -    | $\pm 100$ | nA                    |
| Zero gate voltage drain current           | $I_{DSS}$             | $V_{DS} = 500\text{ V}$ , $V_{GS} = 0\text{ V}$  |  | -    | -    | 25        | $\mu\text{A}$         |
|   |                       | $V_{DS} = 400\text{ V}$ , $V_{GS} = 0\text{ V}$ , $T_J = 125\text{ }^{\circ}\text{C}$  |  | -    | -    | 250       |                       |
| Drain-source on-state resistance          | $R_{DS(on)}$          | $V_{GS} = 10\text{ V}$   | $I_D = 8.4\text{ A}^b$   | -    | -    | 0.450     | $\Omega$              |
| Forward transconductance                  | $g_{fs}$              | $V_{DS} = 50\text{ V}$ , $I_D = 8.4\text{ A}$  |  | 8.1  | -    | -         | S                     |
| Dynamic                                   |                       |  |  |      |      |           |                       |
| Input capacitance                         | $C_{iss}$             | $V_{GS} = 0\text{ V}$ ,<br>$V_{DS} = 25\text{ V}$ ,<br>$f = 1.0\text{ MHz}$ , see fig. 5   |  | -    | 1910 | -         | pF                    |
| Output capacitance                        | $C_{oss}$             |  |  | -    | 290  | -         |                       |
| Reverse transfer capacitance              | $C_{rss}$             |  |  | -    | 11   | -         |                       |
| Output capacitance                        | $C_{oss}$             | $V_{GS} = 0\text{ V}$  | $V_{DS} = 1.0\text{ V}$ , $f = 1.0\text{ MHz}$   | -    | 2730 | -         | pF                    |
| Effective output capacitance              | $C_{oss\text{ eff.}}$ |  | $V_{DS} = 400\text{ V}$ , $f = 1.0\text{ MHz}$   | -    | 82   | -         |                       |
|   |                       |  | $V_{DS} = 0\text{ V to } 400\text{ V}^c$   | -    | 160  | -         |                       |
| Total gate charge                         | $Q_g$                 | $V_{GS} = 10\text{ V}$   | $I_D = 14\text{ A}$ , $V_{DS} = 400\text{ V}$ ,<br>see fig. 6 and 13 <sup>b</sup>                          | -    | -    | 81        | nC                    |
| Gate-source charge                        | $Q_{gs}$              |  |  | -    | -    | 20        |                       |
| Gate-drain charge                         | $Q_{gd}$              |  |  | -    | -    | 36        |                       |
| Turn-on delay time                        | $t_{d(on)}$           |  | $V_{DD} = 250\text{ V}$ , $I_D = 14\text{ A}$ ,<br>$R_g = 7.5\text{ }\Omega$ ,<br>see fig. 10 <sup>b</sup> | -    | 15   | -         | ns                    |
| Rise time                                 | $t_r$                 |  |  | -    | 39   | -         |                       |
| Turn-off delay time                       | $t_{d(off)}$          |  |  | -    | 39   | -         |                       |
| Fall time                                 | $t_f$                 |  |  | -    | 31   | -         |                       |
| Gate input resistance                     | $R_g$                 | $f = 1\text{ MHz}$ , open drain  |  | 0.5  | -    | 2.1       | $\Omega$              |
| Drain-Source Body Diode Characteristics   |                       |  |  |      |      |           |                       |
| Continuous source-drain diode current     | $I_S$                 | MOSFET symbol<br>showing the<br>integral reverse<br>p - n junction diode   |  | -    | -    | 14        | A                     |
| Pulsed diode forward current <sup>a</sup> | $I_{SM}$              |  |  | -    | -    | 56        |                       |
| Body diode voltage                        | $V_{SD}$              | $T_J = 25\text{ }^{\circ}\text{C}$ , $I_S = 14\text{ A}$ , $V_{GS} = 0\text{ V}^b$   |  | -    | -    | 1.5       | V                     |
| Body diode reverse recovery time          | $t_{rr}$              | $T_J = 25\text{ }^{\circ}\text{C}$ , $I_F = 14\text{ A}$ ,<br>$T_J = 125\text{ }^{\circ}\text{C}$ , $dI/dt = 100\text{ A}/\mu\text{s}^b$ |  | -    | 370  | 550       | ns                    |
| Body diode reverse recovery charge        | $Q_{rr}$              |  |  | -    | 4.4  | 6.5       | $\mu\text{C}$         |
| Body diode reverse recovery current       | $I_{RRM}$             |  |  | -    | 21   | 31        | A                     |
| Forward turn-on time                      | $t_{on}$              | Intrinsic turn-on time is negligible (turn-on is dominated by $L_S$ and $L_D$ )  |  |      |      |           |                       |

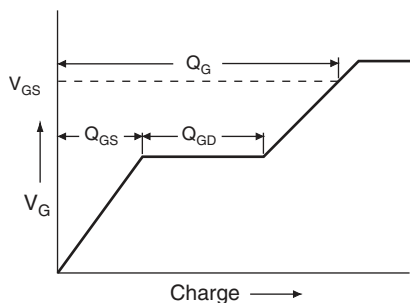
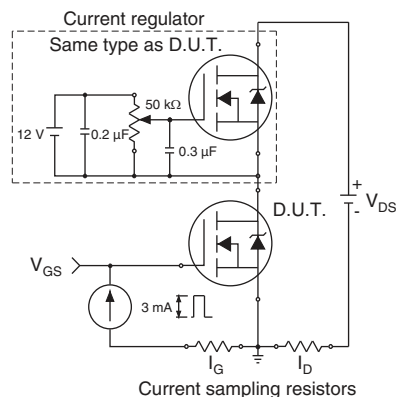
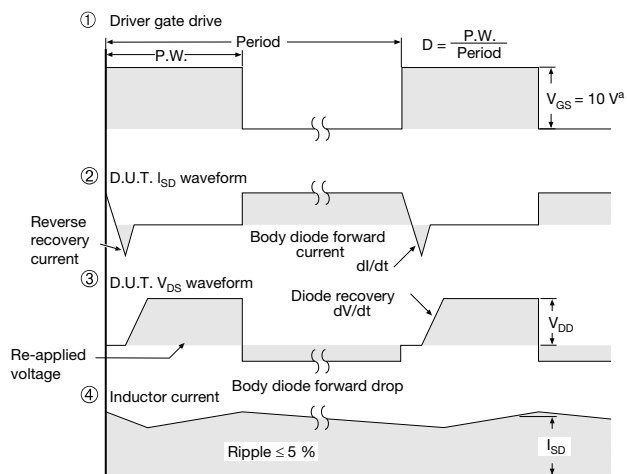
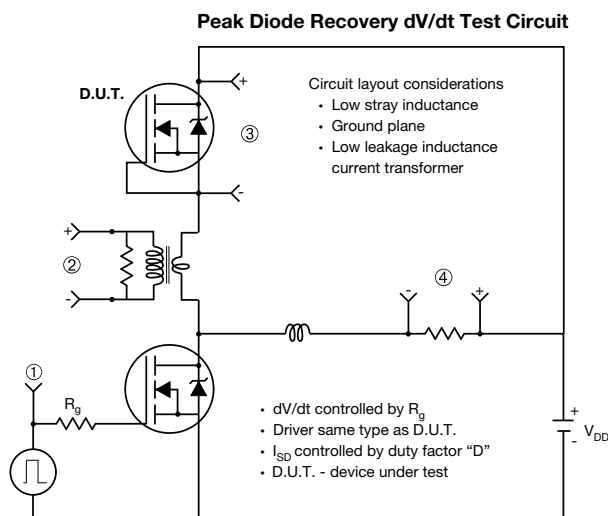
**Notes**

- a. Repetitive rating; pulse width limited by maximum junction temperature (see fig. 11)  
b. Pulse width  $\leq 300\text{ }\mu\text{s}$ ; duty cycle  $\leq 2\%$   
c.  $C_{oss\text{ eff.}}$  is a fixed capacitance that gives the same charging time as  $C_{oss}$  while  $V_{DS}$  is rising from 0 % to 80 %  $V_{DS}$

**TYPICAL CHARACTERISTICS** (25 °C, unless otherwise noted)

**Fig. 1 - Typical Output Characteristics**

**Fig. 4 - Normalized On-Resistance vs. Temperature**

**Fig. 2 - Typical Output Characteristics**

**Fig. 5 - Typical Capacitance vs. Drain-to-Source Voltage**

**Fig. 3 - Typical Transfer Characteristics**

**Fig. 6 - Typical Gate Charge vs. Gate-to-Source Voltage**


**Fig. 7 - Typical Source-Drain Diode Forward Voltage**

**Fig. 8 - Maximum Safe Operating Area**

**Fig. 9 - Maximum Drain Current vs. Case Temperature**

**Fig. 10a - Switching Time Test Circuit**

**Fig. 10b - Switching Time Waveforms**


**Fig. 11 - Maximum Effective Transient Thermal Impedance, Junction-to-Case**

**Fig. 12a - Unclamped Inductive Test Circuit**

**Fig. 12b - Unclamped Inductive Waveforms**

**Fig. 12c - Maximum Avalanche Energy vs. Drain Current**


**Fig. 13a - Basic Gate Charge Waveform**

**Fig. 13b - Gate Charge Test Circuit**


**Note**  
a.  $V_{GS} = 5 V$  for logic level devices

**Fig. 14 - For N-Channel**

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